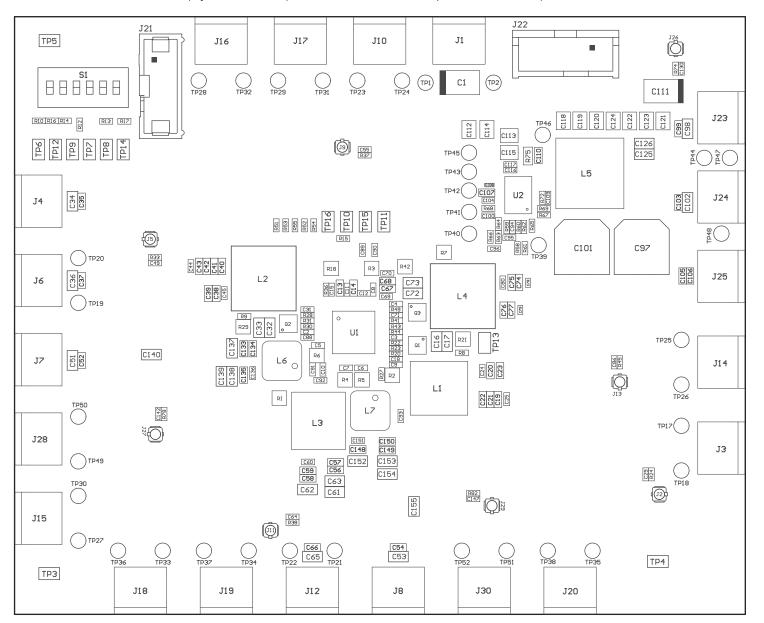
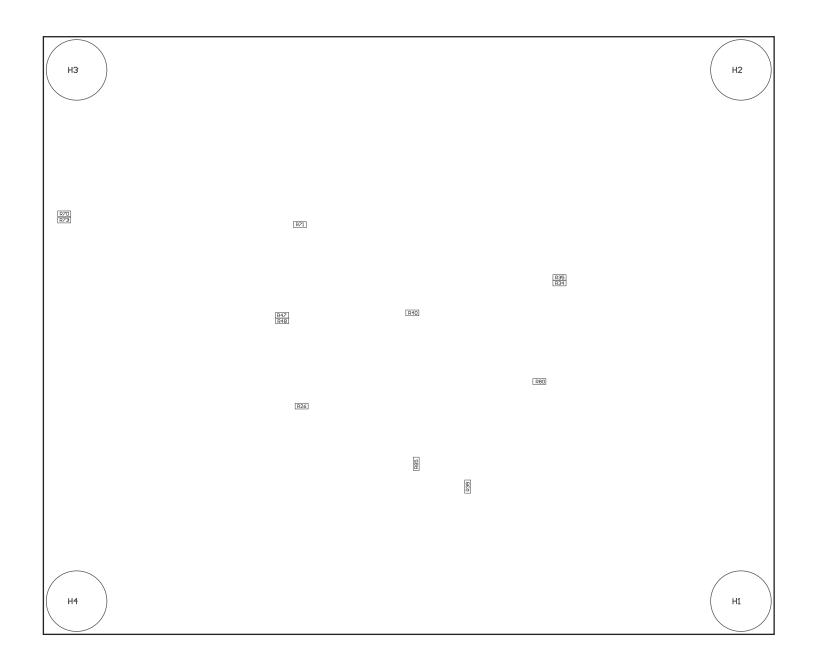
ZZ1 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZZ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



| PCB VIEWED FROM TOP SIDE | BOARD #: | PMP12004- | REU: Revâ | SUN REV | : Not In VersionControl | | |
|------------------------------|--------------------|------------|-----------|---------|-------------------------|--|--|
| LAYER NAME = M5 Assembly Top | TID #: PMP12004-HE | | | | | | |
| | GENERATE | D : 3/30/2 | 2:10:31 | AM | TEXAS INSTRUMENTS | | |



| PCB VIEWED FROM BOTTOM SIDE | BOARD #: | PMP12004- | RE | J: RevA | SUN REV | : Not In VersionControl | |
|---------------------------------|--------------------|-----------|-----|---------|---------|-------------------------|--|
| LAYER NAME = M6 Assembly Bottom | TID #: PMP12004-HE | | | | | | |
| | GENERATED | 3/30/2 | 016 | 2:10:32 | AM | TEXAS INSTRUMENTS | |

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